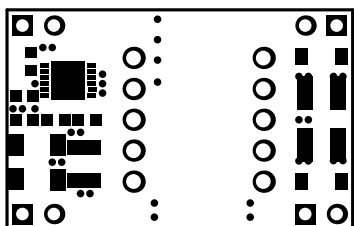
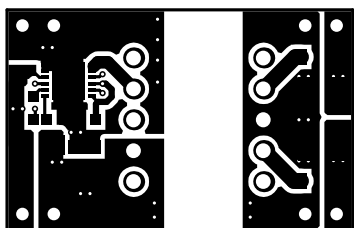


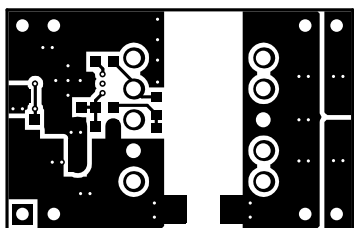
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10654	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP10654		
PLOT NAME = Top Overlay	GENERATED : 5/6/2015	10:43:48 AM	TEXAS INSTRUMENTS



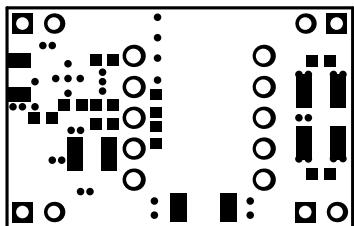
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10654	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP10654		
PLOT NAME = Top Solder Mask	GENERATED : 5/6/2015	10:43:50 AM	TEXAS INSTRUMENTS



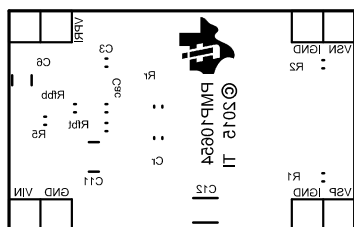
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10654	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP10654		
PLOT NAME = Top Layer	GENERATED : 5/6/2015	10:43:51 AM	TEXAS INSTRUMENTS



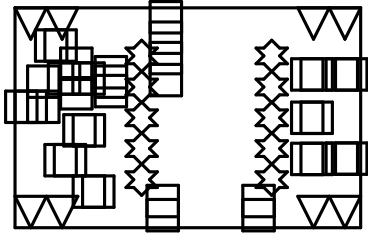
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10654	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP10654		
PLOT NAME = Bottom Layer	GENERATED : 5/6/2015	10:43:52 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10654	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP10654		
PLOT NAME = Bottom Solder Mask	GENERATED : 5/6/2015	10:43:53 AM	TEXAS INSTRUMENTS

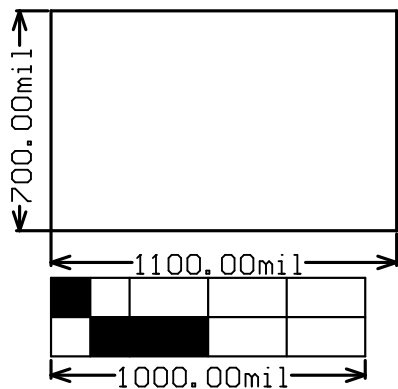


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10654	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: PMP10654		
PLOT NAME = Bottom Overlay	GENERATED : 5/6/2015	10:43:54 AM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
□	38	10.00mil (0.254mm)	PTH	Round
▽	8	40.00mil (1.016mm)	PTH	Round
☆	10	47.24mil (1.200mm)	PTH	Round
	56 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10654	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP10654		
PLOT NAME = Drill Drawing	GENERATED : 5/6/2015	10:43:55 AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10654	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP10654		
PLOT NAME = Board Dimensions	GENERATED : 5/6/2015	10:43:57 AM	TEXAS INSTRUMENTS



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